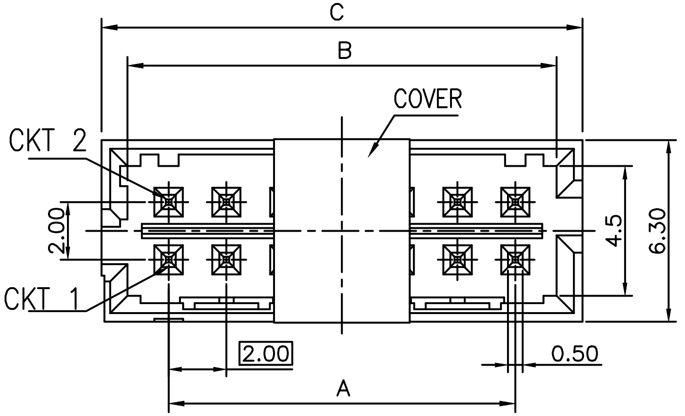
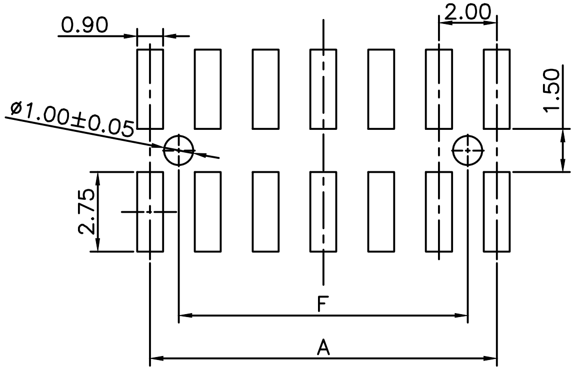




RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

NOTES:

1. MATERIAL:
   - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR BLACK
   - 1.2 TERMINAL: COPPER ALLOY
2. FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.
   - 2.1 CONTACT AREA:
     - 1: G/F
     - C: GOLD 15u"
     - D: GOLD 30u"
     - N: 80U"MIN MATTE TIN
   - 2.2 SOLDER AREA:
     - MATTE TIN
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51386-XXXXX-XXX
5. PART NUMBER

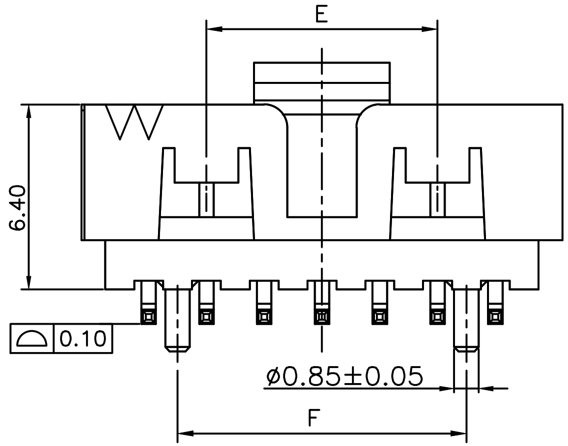
51386-XXX X X-XXX

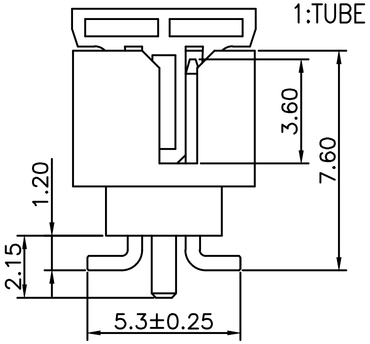
CKTS

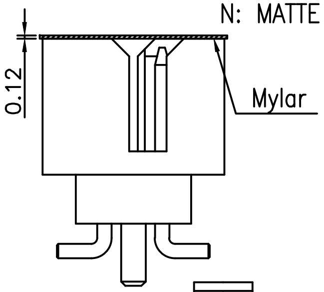
PACKING
4:TAPE&REEL WITH MYLAR
7:TAPE&REEL WITH COVER
1:TUBE

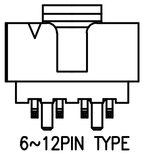
PLATING
1: G/F
C: GOLD 15u"
D: GOLD 30u"
N: MATTE TIN

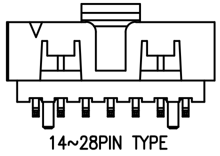
XXX	POLARIZATION	CENTER LOCK	OTHER	PACKING
001	WITH BOSS	NO	WITH COVER 51351-xxxCxxx-001	51386-XXXXX-00-TRP
002	WITH BOSS	NO	WITH Maylar	51386-XXXXX-05-TRP
003	WITHOUT BOSS	NO	WITH COVER 51351-xxxCxxx-001	51386-XXXXX-00-TRP
004	WITHOUT BOSS	NO	WITH COVER 51351-xxxCxxx-001	51386-XXXXX-01-TRP



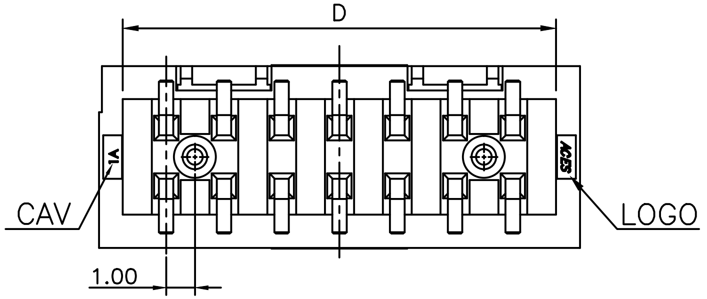


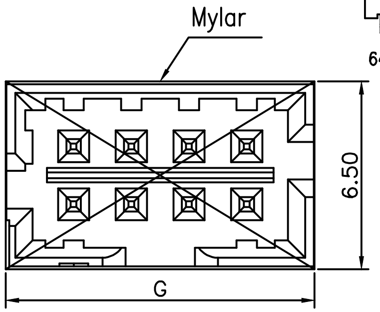



6~12PIN TYPE


14~28PIN TYPE

CKT	DIM A	DIM B	DIM C	DIM D	DIME	DIM F	Mylar DIM G
6	4.0	6.85	8.65	7.0	-	2.0	NA
8	6.0	8.85	10.65	9.0	-	4.0	10.7
10	8.0	10.85	12.65	11.0	-	6.0	NA
12	10.0	12.85	14.65	13.0	-	8.0	NA
14	12.0	14.85	16.65	15.0	8.00	10.0	NA
16	14.0	16.85	18.65	17.0	10.00	12.0	NA
18	16.0	18.85	20.65	19.0	12.00	14.0	NA
20	18.0	20.85	22.65	21.0	14.00	16.0	NA
24	22.0	24.85	26.65	25.0	18.00	20.0	NA
28	26.0	28.85	30.65	29.0	22.00	24.0	NA





QUALITY SYMBOLS
MAJOR Ⓜ
CRITICAL Ⓒ
GENERAL TOLERANCES
(UNLESS SPECIFIED)
X. ±0.5
.X ±0.25
.XX ±0.15
.XXX ±0.1
ANGLES ±2°

DRAWN BY	Zhang,hongjun	DATE 21'/11/06
CHECKED BY	Lu, Jing Quan	DATE 21'/11/06
APPROVED BY	hsieh, fu yu	DATE 21'/11/06

ACES ELECTRONICS

TITLE
2.0mm WTB WAFER CONN
SMT D/R S/T TYPE

UNITS		SIZE	RFQ NO.
mm	⊕◁	A4	N/A
SCALE	**SHEET NO.**	**REV**	**DWG NO.**
2 : 1	1 OF 1	B	51386-XXXXX-XXX